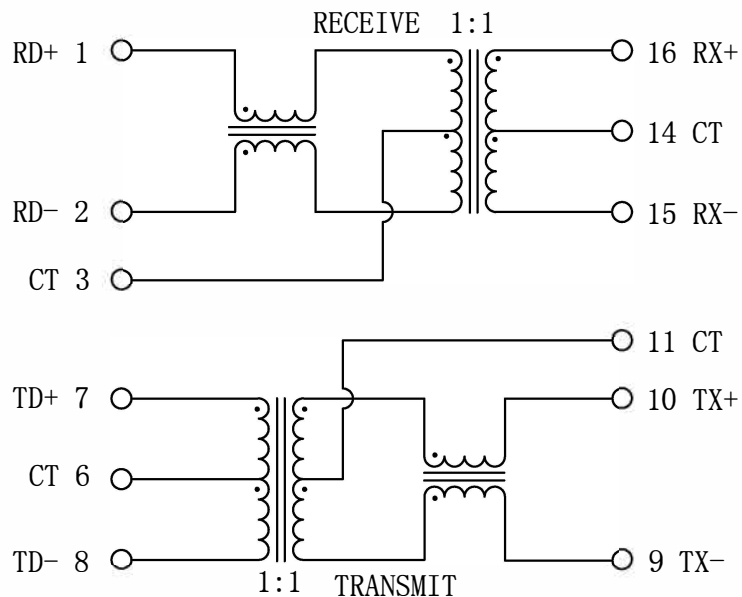


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL	Pulse H0009NL alternative	01/09/2009	



Electrical Specifications @25°C

1. OCL: 350uH MIN
@100KHz 0.1Vrms
2. Turns Ratio(±5%):
TX = 1:1 RX = 1:1
3. Insertion Loss(dB MAX):
100KHz-100MHz:-0.9
4. Return Loss(dB MIN):
30MHz:-16 60MHz:-12
80MHz:-11
5. Differential to Common Mode Rejection
(dB MIN):
30MHz:-35 50MHz:-33
100MHz:-20
6. Crosstalk(dB MIN):
30MHz:-50 62MHz:-45
100MHz:-40
7. Hipot: 1500Vrms MIN
8. Operating Temperature: 0°C~70°C.

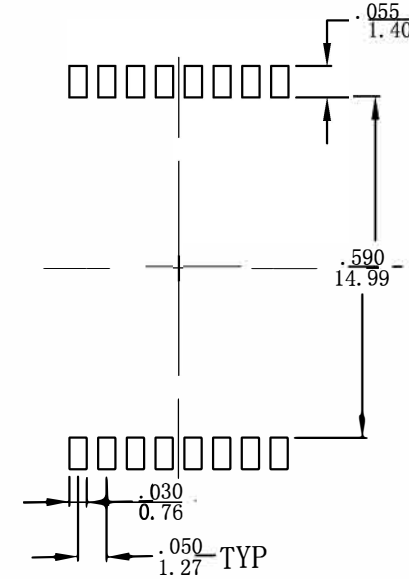
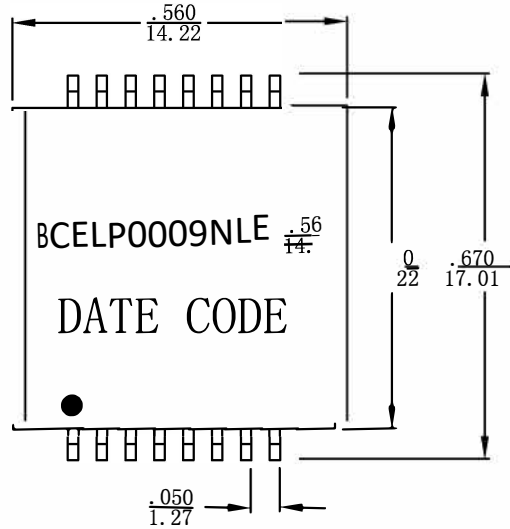
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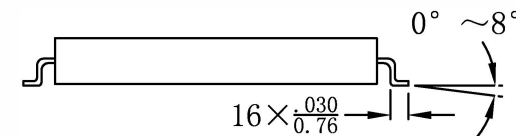
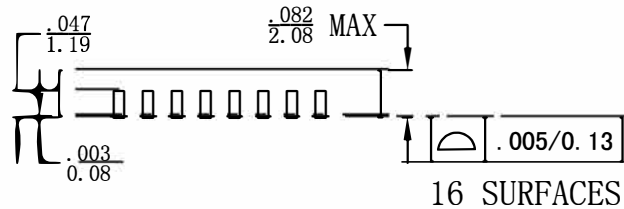
X:X	±0.20	APPD:	Pulse H0009NL alternative by BEC Distribution Ltd	
X:XX	±0.10	CHKD:	TITLE: 10/100 PC CARD LAN MAGNETICS MODULES	
X:XXX	±0.05	DR: TOM	PART NO.: BCEL P0009NLE	
ANGLES	±1°	UNIT: mm		
	SCALE: 2/1	SHEET: 1/2	REV: A	DWG NO.: LP09090115

Mechanical :

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL	Pulse H0009NL alternative b	01/09/2009	



SUGGESTED PAD LAYOUT



NOTES:

1. Peak solder temperature rating per Tabel5-20 in IPC/JEDED J-STD-020C
2. Low profile packages from $.094$ " (2.39mm) to $.078$ " (1.98mm) for PC card and cardbus applications
3. Compliant with IEEE802.3u

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X:X	± 0.20	APPD:	Pulse H0009NL alternative by BEC Distribution Ltd
X:XX	± 0.10	CHKD:	
X:XXX	± 0.05	DR: TOM	TITLE: 10/100 PC CARD LAN MAGNETICS MODULES
ANGLES	$\pm 1^\circ$	UNIT: mm	PART NO.: BCEL P0009NL
	SCALE: 2/1	SHEET: 2/2	REV: A DWG NO.: LP09090115